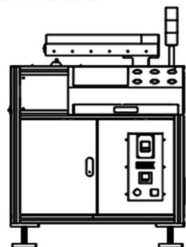


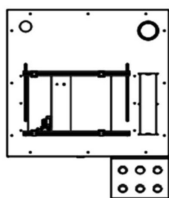
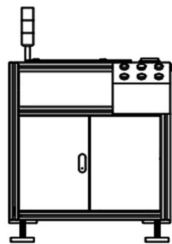
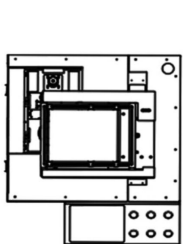
技术参数 Technical parameters

	焊接 Welder : SW-300S		喷雾 Sprayer : SW-300F
长×宽×高 (L×W×H)	750×900×1250 mm 含三色灯 X 轴伸出后(长度:910mm) With tri-color lights After axis X extends(Length:910mm)	长×宽×高 (L×W×H)	750×900×1250 mm (含三色灯 With tri-color lights)
重量 Weight	145KG	重量 Weight	95KG
锡炉容量 Soldering furnace capacity	16KG	助焊剂容量 Flux capacity	2L
锡炉材质 Material of soldering furnace	钛合金材料(适用有铅和无铅焊锡)/Titanium alloy material (applicable to lead and lead-free solder)	助焊剂喷嘴 Flux spray nozzle	0.5mm日本原装精密液体雾化喷嘴 0.5mm Japan-originated precision liquid spraying nozzle
焊嘴 Welding nozzle	直径3mm-20mm 可根据要求定制焊嘴/Dia.3mm-20mm Nozzle can be customized by requirements	气源用量 Air source consumption	20升/分钟/20 Litres/minute
氮气用量 Nitrogen consumption	30升/分钟, 5 bar压力/30 Litres/minute, 5 bar pressure	气源压力 Air source pressure	0.4Mpa-0.5Mpa (压力 Pressure)
氮气纯度 Nitrogen purity	99.99%以上/Above 99.99%	喷雾功率 Spray power	0.5KVA
焊接功率 Welding power	3.5KVA 含底部红外预热/3.5KVA including infrared preheating in the bottom		
电源 Power	单相交流 208V-250V 50/60Hz/Single phase Alternating Current: 208V-250V 50/60Hz		
PCB板焊接尺寸 PCB board welding size	300mm*250mm		
板边距离 Distance of board edge	上 / 下3mm /Top/Bottom 3mm		
PCB 板上下净空 Top/bottom clearance of PCB board	上 / 下30mm (参考) /Top/Bottom 30mm (for reference)		
X / Y / Z 轴精度 X / Y / Z Accuracy of axis	0.1mm		
重复精度 Repeat accuracy	+/-0.05mm		
放板方式 Mode of placing PCB board	手动放板/Manually		
PCB 板定位方式 Positioning mode of PCB board	可调式 PCB 板定位框架, 带活动支架/Adjustable PCB positioning frame with movable bracket		
编程 Programming	基于 Windows 系统开发的 Singrain SS 编程软件/singrain SS programming software developed on the basis of Windows system		
离线编程 Offline programming	支持离线图片画线编程/Support line drawing programming of offline pictures		

SW-300S



SW-300F



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深圳新锐自动化 13602606340



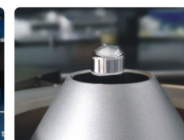
灵活

离线型

可快速

换板的选择性波峰焊系统

Flexible, Offline, Fast Board-changing Selective Wave Soldering System



深圳市新锐自动化设备有限公司

SHENZHEN SINGRAIN AUTOMATION EQUIPMENT CO.,LTD.

灵活、离线型、可快速换板的选择性波峰焊系统

Flexible, Offline, Fast Board-changing Selective Wave Soldering System



是一款离线型落地式选择性波峰焊，专为小批量品种生产的客户而设计，设备分喷雾机和焊接机为一整套，也可一托二的方式配置，提高生产效率，满足客户的需求。

为提高焊接品质，焊接机设有氮气保护、PCB板预热、波峰高度监测等功能，满足不同PCB板工艺需求。

It is a type of offline floor-standing selective wave soldering, which is designed for customers with small batch production. This equipment is a complete set divided into a sprayer and a welding machine. It can also be configured in a way of "one for two" to improve production efficiency and meet the needs of customers.

In order to improve the welding quality, the welding machine is equipped with functions such as nitrogen protection, PCB board preheating, crest and peak height monitoring, etc. to meet the processing requirements of different PCB boards.

操作界面 Operation interface

由一台装有SingRain SS 软件的电脑控制，该软件基于Windows系统开发，可以导入离线编程预先处理好的文件。此外，SingRain offLine program软件可以通过导入PCB板图片资料实现离线编程。

It is controlled by a computer installed with SingRain SS software, which is developed on the basis of Windows system and it can import pre-processed files for offline programming. In addition, the software "SingRain OffLine Program" can realize offline programming by importing the pictures information of PCB boards.



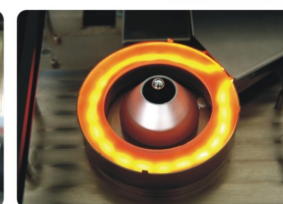
编程界面 Programming interface

开放式编程方式，可灵活实现各种焊接及收锡方式，可在线修改程序和在线编程。

The open programming mode can freely realize various welding and tin collecting modes, and it can modify the program and program online.



波峰高度自动检测补偿
Automatic detection and compensation of peak height



红外线PCB板预热
Infrared PCB preheating



助焊剂恒压箱
Constant pressure box for flux



助焊剂精密雾化喷头
Precision atomizing nozzle for flux



氮气流量监测
Nitrogen flow monitoring

选择性波峰焊机的特点 Features of selective wave soldering machine

节能：设备运行功率低，工作功率1.5KW，16KG焊锡炉，焊锡一次性投入低。

高品质：可控制每个焊锡点的焊锡量、焊接时间。

程序创建简单化：支持使用PCB图片，离线制作生产程序。

无治具化：可根据焊点大小选择喷嘴，无需对未焊接部位保护，减少治具成本。

锡渣产生量低：焊锡渣产生量控制0.2kg / 8H 以内（氮气保护下）。

通孔透锡率高：通孔透锡率可达99.99%的；焊接良品率可高达98%以上。

生产环保率高：助焊剂用量很少，焊接时烟雾产生少，焊接后电路板整洁度高。

设备利用率高：设备占用空间少，移动灵活，利用率很高。

Energy-saving: The running power of the equipment is low, the operating power is 1.5kw, and the weight of soldering furnace is 16kgs, the soldering investment is low at one time.

High quality: it can control the solder volume and soldering time of each solder point.

Simplified program creation: It supports the use of PCB pictures, and it can make production programs in an offline way.

No fixture: The spray nozzle can be selected according to the size of the soldering point without protecting the unsoldered parts, reducing the cost of fixtures.

Low production of tin dross: The solder dross production is controlled within 0.2kg / 8H (under nitrogen protection).

High rate of through-hole tin penetration: The rate of through-hole tin penetration can reach 99.99%; the soldering yield rate can be as high as more than 98%.

High environmental protection rate for production: the amount of flux use is small, the smoke generation during soldering is low, and the cleanliness of the circuit board after soldering is high

High equipment utilization: The equipment occupies less space and it is moved flexibly with high utilization rate.